GSM3117XF 30V P-Channel MOSFETs

Product Description

These P-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode.

These devices are well suited for high efficiency fast switching applications.

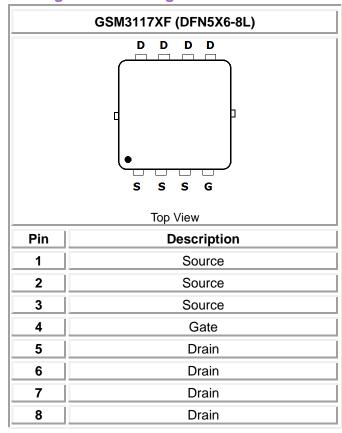
Features

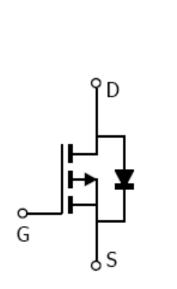
- -30V, -42A, R_{DS(ON)}<14.5mΩ@V_{GS}=-10V
- Fast switching
- Suit for -4.5V Gate Drive Applications
- Green Device Available
- DFN5X6-8L package design

Applications

- MB / VGA / Vcore
- POL Applications
- Load Switch
- LED Application

Packages & Pin Assignments





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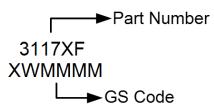


Ordering Information

GS P/N <u>GSM3117 XF</u> Package Code 🚽

Part Number	Package	Quantity Reel	
GSM3117XF	DFN5X6-8L	3000 PCS	

Marking Information



Absolute Maximum Ratings Tc=25°C Unless otherwise noted

Symbol	Parameter		Typical	Unit
VDS	Drain-Source Voltage		-30	V
V _{GS}	Gate-Source Voltage		±25	V
	Continuous Drain Current ¹	Tc=25°C	-42	А
ID		Tc=100°C	-27	
Ідм	Pulsed Drain Current		-140	Α
Eas	Single Pulse Avalanche Energy ²		18	mJ
Pp	Power Dissipation ¹	T _C =25°C	42	w
PD		Tc=100°C	17	V
TJ	Operating Junction Temperature Range		-55 to +150	°C
T _{STG}	Storage Temperature Range		-55 to +150	°C
R _{θJA}	Thermal Resistance-Junction to Ambient ¹		50	°C/W
R _{ejc}	Thermal Resistance-Junction to Case		3	°C/W



Electrical Characteristics

T_J=25°C Unless otherwise noted

Symbol	Parameter	Parameter Conditions		Тур	Мах	Unit	
Static characteristics							
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =-250uA	-30			V	
V _{GS(th)}	Gate Threshold Voltage V _{DS} =V _{GS} , I _D =-250uA		-1.2	-1.6	-2.5	V	
Igss	Gate Leakage Current	V _{DS} =0V, V _{GS} =±25V			±100	nA	
IDSS	Drain-Source Leakage Current	V _{DS} =-30V, V _{GS} =0V			-1	uA	
Vsd	Diode Forward Voltage ³	Vgs=0V, Is=-1A			-1	V	
D		V _{GS} =-10V, I _D =-10A		11.9	14.5	mΩ	
RDS(on)	Drain-Source On-Resistance ³	V _{GS} =-4.5V, I _D =-6A		19	23		
Gate charge characteristics							
Qg	Total Gate Charge			22		nC	
Q_{gs}	Gate-Source Charge	V _{DD} =-15V, V _{GS} =-4.5V, I _D =-15A		8.7			
Q_{gd}	Gate-Drain Charge			7.2			
	Dynam	ic characteristics					
Ciss	Input Capacitance			2215		pF	
Coss	Output Capacitance	V _{DS} =-15V,V _{GS} =0V, f=1.0MHz		310			
Crss	Reverse Transfer Capacitance	1=1.00012		237			
t _{d(on)}	Turn-On Time			8		ns	
tr	Rise Time	V _{DD} =-15V, V _{GS} =-10V,		73.7			
t _{d(off)}	Turn-Off Time	Rg=3.3Ω, I _D =-15A		61.8			
tr	Fall Time			24.4			

Note

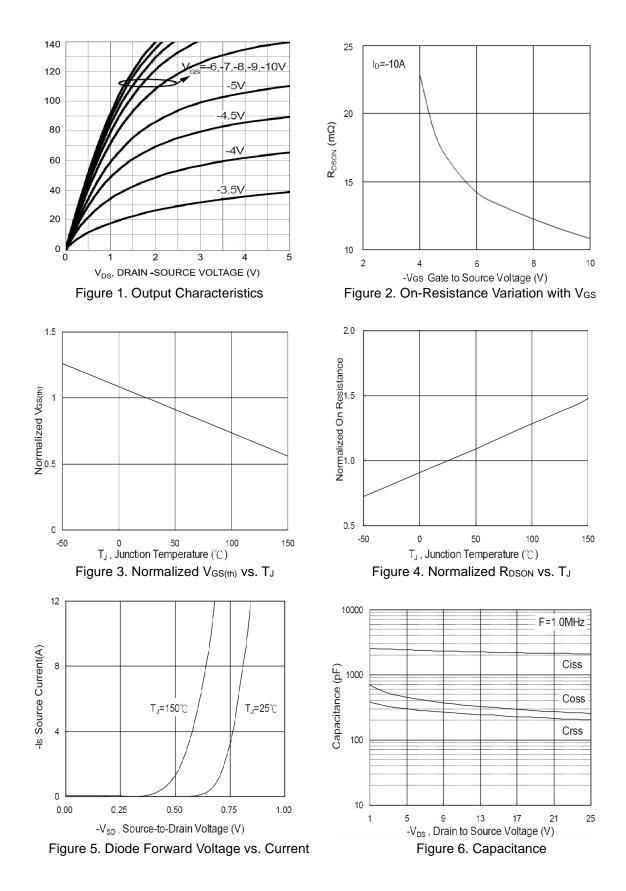
1. The data tested by surface mounted on a 1 inch² FR-4 board with 2oz copper. 2. The E_{AS} data shows Max. rating . The test condition is V_{DD} =-20V, V_{GS} =-10V, L=0.1mH, I_{AS}=-19A.

3. The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%.



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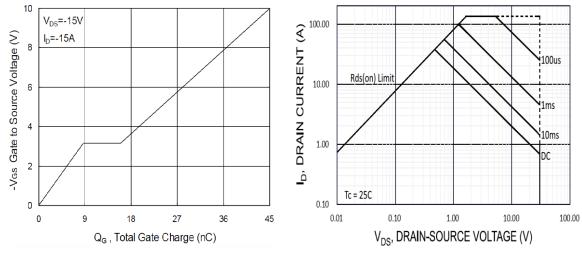
Typical Performance Characteristics



GSM3117XF

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Typical Performance Characteristics (Continue)

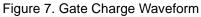
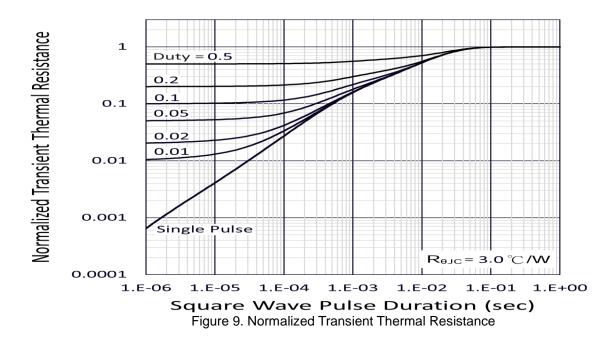


Figure 8. Maximum Safe Operating Area

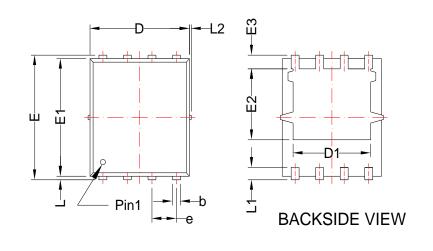


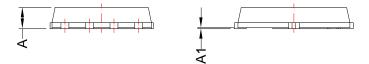


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Package Dimension

DFN5X6-8L





DIMENSION D AND E1 DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL HOT EXCEED 0.5mm PER INTERLEAD FLASH OR PROTRUSIOB SHALL NOT EXCEED 0.5mm PER SIDE.

	Dimensions				
CYMDOL	Millimeters		Inches		
SYMBOL	MIN	MAX	MIN	MAX	
Α	0.80	1.20	0.031	0.047	
A1	0.00	0.05	0.000	0.002	
b	0.25	0.51	0.010	0.020	
С	0.20	0.35	0.008	0.014	
D	4.90	5.40	0.193	0.213	
D1	3.40	4.60	0.134	0.181	
е	1.27 BSC		0.050) BSC	
L	0.1	0.25	0.004	0.010	
L1	0.45	0.75	0.018	0.030	
L2		0.15		0.006	



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